



## Final Product Change Notification

201503014F01

**Issue Date:** 24-Mar-2015

**Effective Date:** 06-Jul-2015

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# QUALITY

### Management Summary

UBA2014T/N1 changeover to High Density Matrix Leadframe APB (package SO16).

#### Change Category

<input type="checkbox"/> Wafer Fab process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab materials	<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Electrical spec./Test coverage	<input type="checkbox"/> Mechanical Specification
<input type="checkbox"/> Wafer Fab location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Test Location	<input type="checkbox"/> Packing/Shipping/Labeling

## UBA2014TT/N1 High Density Matrix Leadframe

### Details of this Change

Production of the UBA2014T/N1 product will be transferred to the high density lead frame line. This results in a slight modification of the inner lead frame design. The package outline and dimensions will not change, as well as the solder conditions.

#### Why do we Implement this Change

In the NXP assembly site APB Bangkok the so-called matrix lead frame assembly lines will be replaced by high density matrix lines.

#### Identification of Affected Products

Product identification does not change

### Product Availability

#### Sample Information

Samples are available upon request

#### Production

Planned first shipment 24-Jun-2015

#### Impact

no impact to the product's functionality anticipated.

#### Data Sheet Revision

No impact to existing datasheet

#### Disposition of Old Products

Existing inventory will be shipped until depleted

#### Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 23-Apr-2015.

n.a.

#### Remarks

n.a.

## Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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